

## CLAIMS

1. A method to elongate a solder joint, the method comprising:  
forming an elongator on a first substrate, wherein the elongator comprises an  
5 expander and an encapsulant to encapsulate the expander;  
forming the solder joint to connect the first substrate to a second substrate; and  
softening the encapsulant to release the expander from a compressed state to  
elongate the solder joint.
- 10 2. The method to elongate a solder joint as recited in claim 1, wherein  
forming the elongator on the first substrate comprises:  
providing a mold having a first mold cavity and a second mold cavity, wherein the  
first substrate is disposed in the first mold cavity and an expander is disposed in the  
second mold cavity;  
15 compressing the expander; and  
introducing the encapsulant into the mold to encapsulate the expander to form the  
elongator on the first substrate.
- 20 3. The method to elongate a solder joint as recited in claim 2, further  
comprising:  
singulating the first substrate.
- 25 4. The method to elongate a solder joint as recited in claim 3, wherein the  
first substrate is one of a group consisting of a series of interposers, a series of packages  
and a wafer.
- 30 5. The method to elongate a solder joint as recited in claim 2, wherein the  
first substrate is one of a group consisting of a chip, an interposer, a package, a board and  
a series of interposers.
6. The method to elongate a solder joint as recited in claim 1, wherein the  
elongator is formed on the first substrate by one of a group consisting of an injection

molding process, a compression molding process, a transfer molding process and a casting process.

7. The method to elongate a solder joint as recited in claim 1, wherein the  
5 encapsulant is an electrical insulator.

8. The method to elongate a solder joint as recited in claim 7, wherein the encapsulant is a thermoplastic.

10 9. The method to elongate a solder joint as recited in claim 8, wherein forming the solder joint to connect the first substrate to the second substrate comprises:  
melting a plurality of solder deposits to wet a solderable surface to form the solder joint.

15 10. The method to elongate a solder joint as recited in claim 9, wherein the thermoplastic has a softening temperature of approximately 40°C higher than a melting point of the plurality of solder deposits.

11. The method to elongate a solder joint as recited in claim 8, wherein the  
20 thermoplastic is one of a group consisting of polyamide and polyacetal.

12. The method to elongate a solder joint as recited in claim 1, wherein the expander comprises a corrugated strip.

25 13. The method to elongate a solder joint as recited in claim 12, wherein a first end of the corrugated strip overlaps a second end of the corrugated strip.

14. A device to elongate a solder joint, the device comprising:  
a substrate; and  
30 an elongator formed on the substrate, wherein the elongator comprises:  
an expander in a compressed state; and  
an encapsulant to encapsulate the expander.

15. The device to elongate a solder joint as recited in claim 14, wherein the substrate is one of a group consisting of a chip, an interposer, a package, a board, a series of interposers, a series of packages and a wafer.

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16. The device to elongate a solder joint as recited in claim 15, wherein the elongator is formed on the substrate by one of a group consisting of an injection molding process, a compression molding process, a transfer molding process and a casting process.

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17. The device to elongate a solder joint as recited in claim 14, wherein the expander comprises a corrugated strip.

18. The device to elongate a solder joint as recited in claim 17, wherein a first  
15 end of the corrugated strip overlaps a second end of the corrugated strip.

19. The device to elongate a solder joint as recited in claim 14, wherein the encapsulant is an electrical insulator.

20. The device to elongate a solder joint as recited in claim 19, wherein the  
20 encapsulant is a thermoplastic.

21. The device to elongate a solder joint as recited in claim 20, wherein the thermoplastic is one of a group consisting of polyamide and polyacetal.

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22. An electronic assembly, comprising:  
a first substrate coupled to a second substrate by a solder joint; and  
an elongator coupled between the first substrate and the second substrate, wherein  
the elongator is formed on the first substrate and wherein the elongator comprises:  
30 an expander; and  
an encapsulant to encapsulate the expander.

23. The electronic assembly as recited in claim 22, wherein the encapsulant is an electrical insulator.

24. The electronic assembly as recited in claim 23, wherein the encapsulant is  
5 a thermoplastic.

25. The electronic assembly as recited in claim 24, wherein the thermoplastic is one of a group consisting of polyamide and polyacetal.

10 26. The electronic assembly as recited in claim 22, wherein the expander comprises a corrugated strip.

27. The electronic assembly as recited in claim 26, wherein a first end of the corrugated strip overlaps a second end of the corrugated strip.  
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28. The electronic assembly as recited in claim 22, wherein the elongator is formed on the first substrate by one of a group consisting of an injection molding process, a compression molding process, a transfer molding process and a casting process.

20 29. The electronic assembly as recited in claim 22, wherein the first substrate is one of a group consisting of a chip, an interposer, a package, a board and a series of interposers.

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